

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10577173
<b>Filing Date:</b>	27-Oct-2009
<b>Title of Invention:</b>	SEMICONDUCTOR DEVICE WITH PLASTIC PACKAGE MOLDING COMPOUND, SEMICONDUCTOR CHIP AND LEADFRAME AND METHOD FOR PRODUCING THE SAME
<b>First Named Inventor/Applicant Name:</b>	Wolfgang Hetzel
<b>Filer:</b>	Mark L. Gleason/Connie Scheff
<b>Attorney Docket Number:</b>	I441.141.101

Filed as Small Entity

### U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
Utility Appl issue fee	2501	1	755	755
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Extension-of-Time:</b>				
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>1055</b>